

HA1630D07

Dual CMOS High Drive Operational Amplifier

REJ03D0859-0200
Rev.2.00
Nov 30, 2007

Description

HA1630D07 is a low power dual CMOS operational amplifier featuring high output current with typical current supply of 120 μ A for both channels (2.7 V to 5.5 V). This IC designed to operate from a single power supply and have full swing outputs. Available in MMPAK-8 and TSSOP-8 package, the miniature size of this IC not only allows compact integration in portable devices but also minimizes distance of signal sources (sensors), thus reducing external noise pick up prior to amplification. This IC exhibit excellent current drive-power ratio capable of 2 k Ω load driving and yet resistant to oscillation for capacitive loads up to 200 pF.

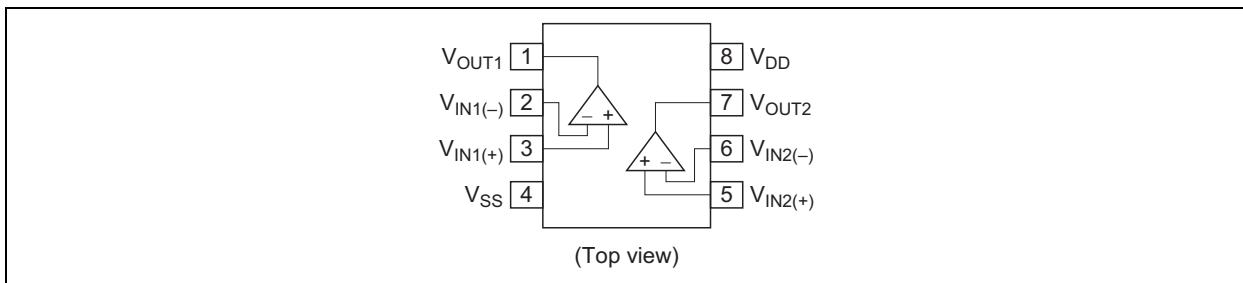
Features

- Low supply current $I_{DD} = 120 \mu\text{A}$ Typ ($V_{DD} = 3 \text{ V}$, $R_L = \text{No load}$)
- Low voltage operation $V_{DD} = 2.7 \text{ V}$ to 5.5 V
- Low input offset voltage $V_{IO} = 6 \text{ mV}$ Max
- Low input bias current $I_{IB} = 1 \text{ pA}$ Typ
- High output current $I_{OSOURCE} = 15 \text{ mA}$ Typ ($V_{DD} = 3.0 \text{ V}$, $V_{OH} = 2.5 \text{ V}$)
 $I_{OSINK} = 15 \text{ mA}$ Typ ($V_{DD} = 3.0 \text{ V}$, $V_{OL} = 0.5 \text{ V}$)
- Input common voltage range includes ground

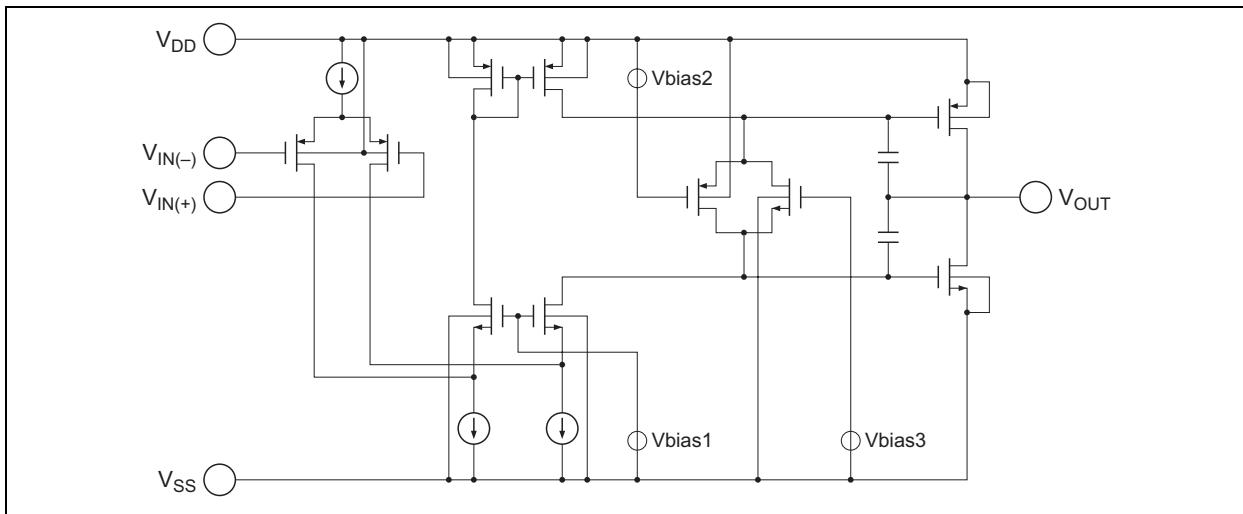
Ordering Information

Part No.	Package Name	Package Code
HA1630D07MM	MMPAK-8	PLSP0008JC-A
HA1630D07T	TSSOP-8	PTSP0008JC-B

Pin Arrangement



Equivalent Circuit (1/2)



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings	Unit	Note
Supply voltage	V _{DD}	7.0	V	
Differential input voltage	V _{IN(dif)}	-V _{DD} to +V _{DD}	V	1
Input voltage	V _{IN}	-0.1 to +V _{DD}	V	
Output current	I _{OUT}	40	mA	
Power dissipation	P _T	145 (MMPAK-8) 192 (TSSOP-8)	mW	2
Operating temperature	T _{opr}	-40 to +85	°C	
Storage temperature	T _{stg}	-55 to +125	°C	

Note: 1. Do not apply input voltage exceeding V_{DD} or 7 V.

2. If Ta > 25°C,

MMPAK-8: derate by -1.45 mW/°C

TSSOP-8: derate by -1.92 mW/°C

Electrical Characteristics

DC Characteristics

(Ta = 25°C, V_{DD} = 3.0 V, V_{SS} = 0 V)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Input offset voltage	V _{IO}	—	—	6	mV	V _{IN} = 1.5 V, R _L = 1 MΩ
Input bias current	I _{IB}	—	(1)	—	pA	V _{IN} = 1.5 V
Input offset current	I _{IO}	—	(1)	—	pA	V _{IN} = 1.5 V
Common mode input voltage range	V _{CM}	-0.1	—	1.8	V	
Supply current	I _{DD}	—	120	340	μA	V _{IN(+)} = 1.0 V, R _L = ∞
Output source current	I _{OSOURCE}	7.5	15	—	mA	V _{OUT} = 2.5 V
Output sink current	I _{OSINK}	7.5	15	—	mA	V _{OUT} = 0.5 V
Open loop voltage gain	A _V	55	80	—	dB	R _L = 100 kΩ
Common mode rejection ratio	CMRR	50	80	—	dB	V _{IN1} = 0 V, V _{IN2} = 1.8 V
Power supply rejection ratio	PSRR	55	80	—	dB	V _{DD1} = 2.7 V, V _{DD2} = 5.5 V
Output high voltage	V _{OH}	2.9	—	—	V	R _L = 2 kΩ to V _{SS}
Output low voltage	V _{OL}	—	—	0.1	V	R _L = 2 kΩ to V _{DD}

Note: () : Design specification

AC Characteristics

(Ta = 25°C, V_{DD} = 3.0 V, V_{SS} = 0 V)

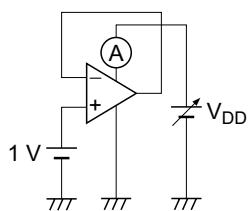
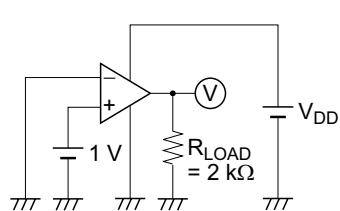
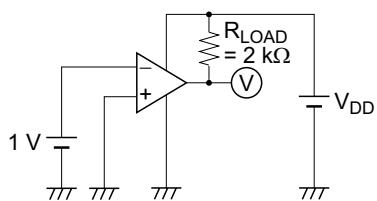
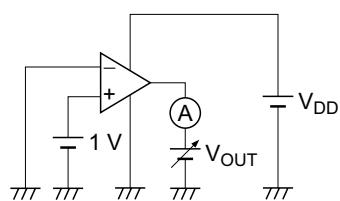
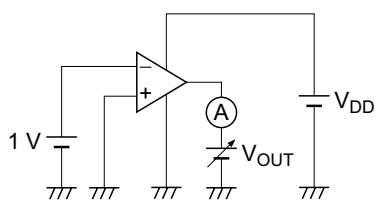
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Slew rate	SRr	—	(1)	—	V/μs	V _{IN} = 1.5 V, C _L = 15 pF (V _{INL} = 0.2 V, V _{INH} = 1.7 V)
	SRf	—	(1)	—		
Gain bandwidth product	GBW	—	(1.5)	—	MHz	V _{IN} = 1.5 V, C _L = 15 pF

Note: () : Design specification

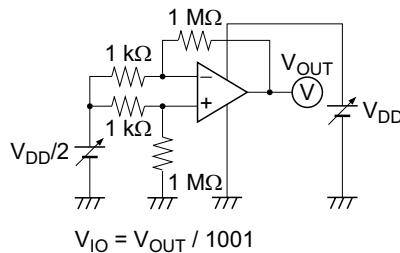
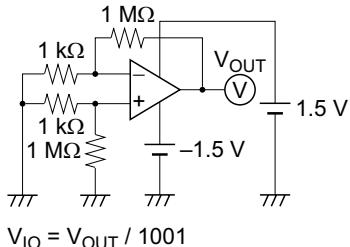
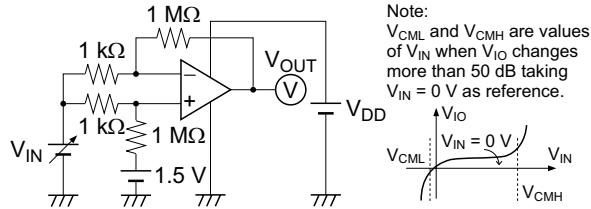
Table of Graphs

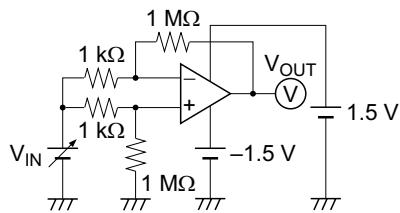
Electrical Characteristics			Characteristic Curves	Test Circuit No.
Supply current	I_{DD}	vs. Supply voltage	1	1
		vs. Temperature	2	1
Output high voltage	V_{OH}	vs. Rload	3	2
Output low voltage	V_{OL}	vs. Rload	4	3
Output source current	$I_{OSOURCE}$	vs. Output high voltage	5	4
		vs. Temperature	6	4
Output sink current	I_{OSINK}	vs. Output low voltage	7	5
		vs. Temperature	8	5
Input offset voltage	V_{IO}	vs. Supply voltage	9	6
		vs. Input voltage	10	6
		vs. Temperature	11	7
Common mode input voltage range	V_{CM}	vs. Supply voltage	12	8
		vs. Temperature	13	8
Common mode rejection ratio	CMRR	vs. Input voltage	14	9
Power supply rejection ratio	PSRR	vs. Supply voltage	15	10
Input bias current	I_{IB}	vs. Input voltage	16	11, 12
		vs. Temperature	17	11, 12
Slew rate (rising)	SR _r	vs. Cload	18	13
		vs. Temperature	19	13
		Time waveform	20	13
Slew rate (falling)	SR _f	vs. Cload	21	13
		vs. Temperature	22	13
		Time waveform	23	13
Open loop gain	A_v	vs. Rload	24	14
		vs. Frequency	25, 26	14
Phase margin	PM	vs. Cload	27	14
Channel separation	CS	vs. Frequency	28	15
Noise input voltage	VNI	vs. Frequency	29	16

Test Circuits

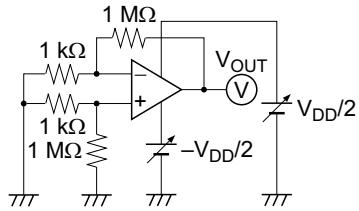
(Unless otherwise noted, $V_{DD} = 3\text{ V}$, $V_{SS} = 0\text{ V}$, $T_a = 25^\circ\text{C}$)1. Supply Current, I_{DD} 2. Output High Voltage, V_{OH} 3. Output Low Voltage, V_{OL} 4. Output Source Current, $I_{OSOURCE}$ 5. Output Sink Current, I_{OSINK} 

6. Input Offset Voltage vs. Operating Voltage

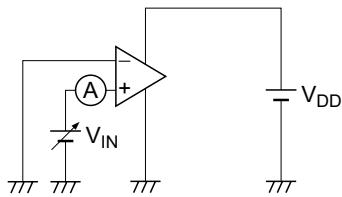
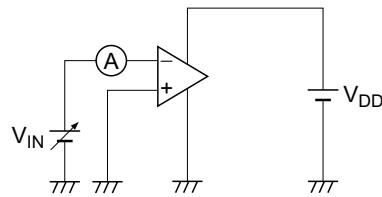
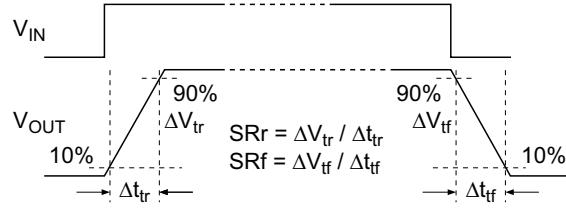
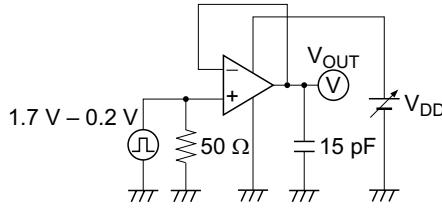
7. Input Offset Voltage, V_{IO} 8. Common Mode Input Voltage Range, V_{CM} 

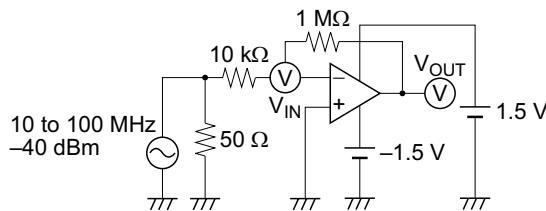
Test Circuits (cont.)(Unless otherwise noted, $V_{DD} = 3\text{ V}$, $V_{SS} = 0\text{ V}$, $T_a = 25^\circ\text{C}$)**9. Common Mode Rejection Ratio, CMRR**

V_{IN}	Measure Point	Calculate V_{IO}	CMRR Calculation
-1.5 V	V_{OUT1}	$V_{IO1} = V_{OUT1} / 1001$	$\text{CMRR} = \left 20 \log_{10} \frac{ V_{IO2} - V_{IO1} }{0.3 - (-1.5\text{ V})} \right $
0.3 V	V_{OUT2}	$V_{IO2} = V_{OUT2} / 1001$	

10. Power Supply Rejection Ratio, PSRR

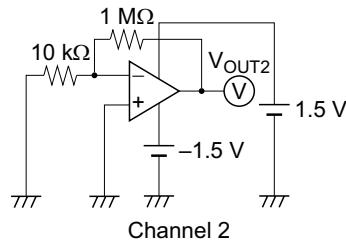
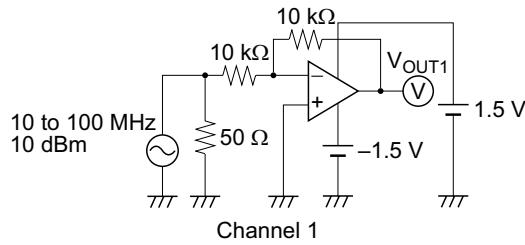
V_{DD}	Measure Point	Calculate V_{IO}	PSRR Calculation
2.7 V	V_{OUT1}	$V_{IO1} = V_{OUT1} / 1001$	$\text{PSRR} = \left 20 \log_{10} \frac{ V_{IO2} - V_{IO1} }{5.5\text{ V} - 2.7\text{ V}} \right $
5.5 V	V_{OUT2}	$V_{IO2} = V_{OUT2} / 1001$	

11. Input Bias Current, I_{IB+} **12. Input Bias Current, I_{IB-}** **13. Slew Rate (Large Signal Input)**

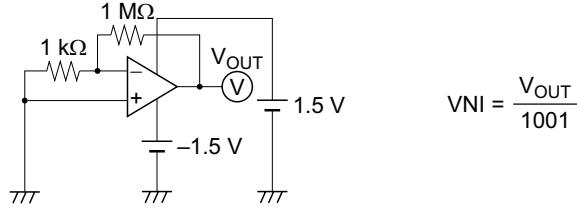
Test Circuits (cont.)(Unless otherwise noted, $V_{DD} = 3\text{ V}$, $V_{SS} = 0\text{ V}$, $T_a = 25^\circ\text{C}$)14. Open Loop Voltage Gain, A_V 

$$A_V = \left| 20\log_{10} \frac{101 \times |V_{OUT}|}{|V_{IN}|} \right|$$

15. Channel Separation, CS



$$CS = \left| 20\log_{10} \frac{101 \times |V_{OUT2}|}{|V_{OUT1}|} \right|$$

16. Noise Input Voltage, V_{NI} 

$$V_{NI} = \frac{|V_{OUT}|}{1001}$$

Characteristic Curves

Figure 1 HA1630D07
Supply Current vs. Supply Voltage

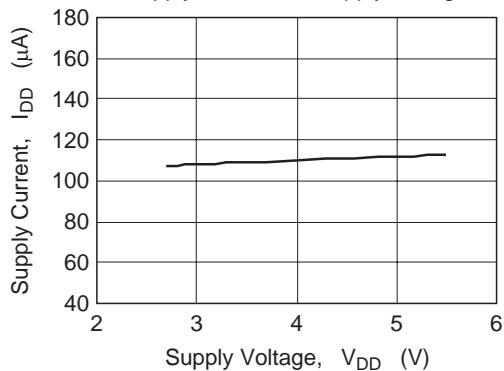


Figure 2 HA1630D07
Supply Current vs. Ambient Temperature

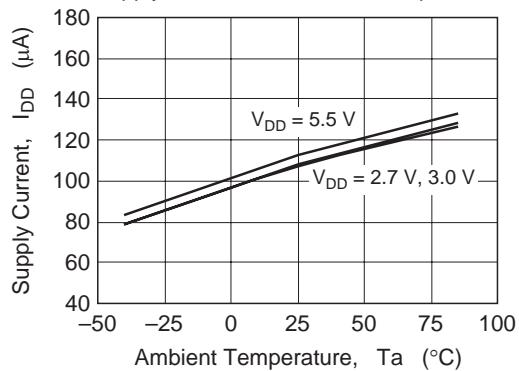


Figure 3 HA1630D07
Output High Voltage vs. Resistor Load

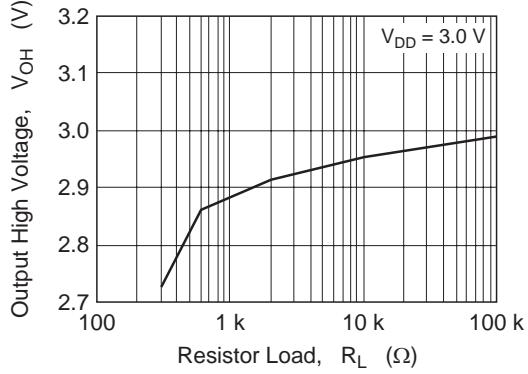


Figure 4 HA1630D07
Output Low Voltage vs. Resistor Load

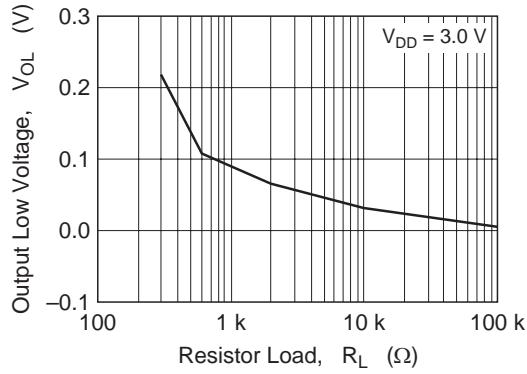


Figure 5 HA1630D07
Output High Voltage vs. Output Source Current

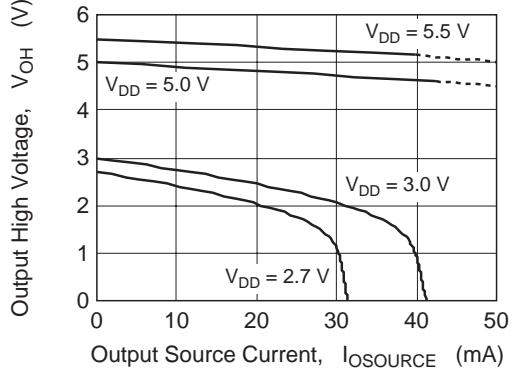
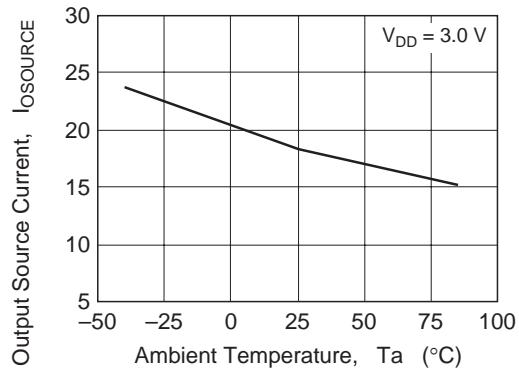
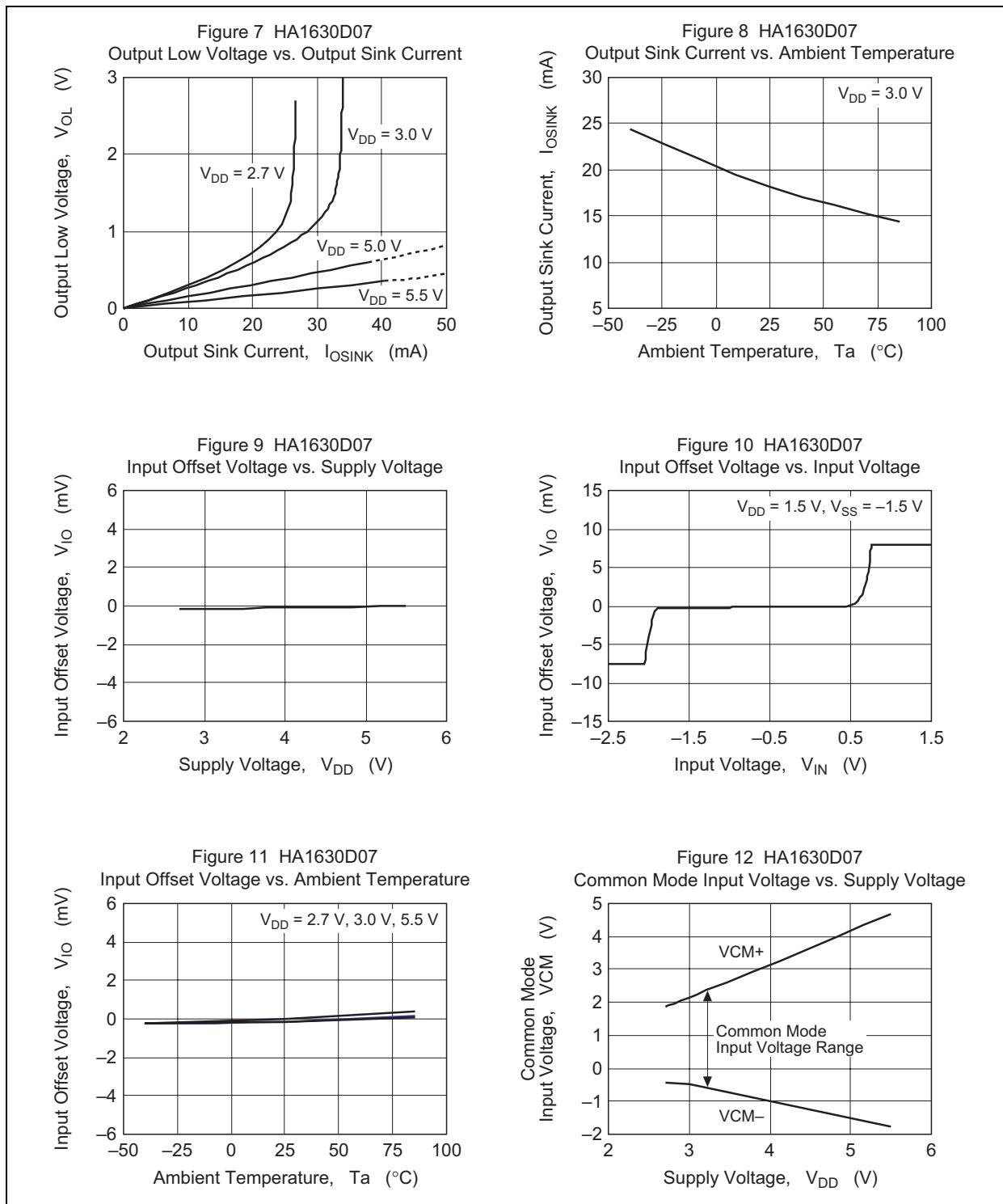


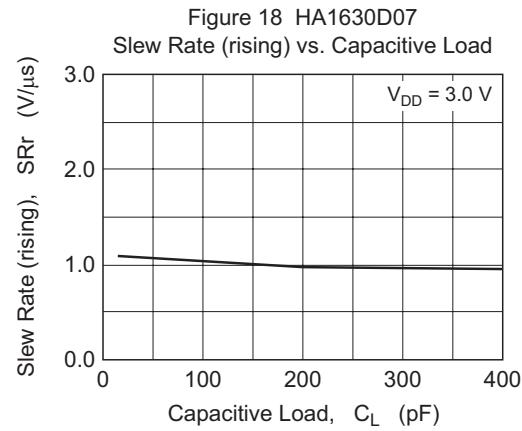
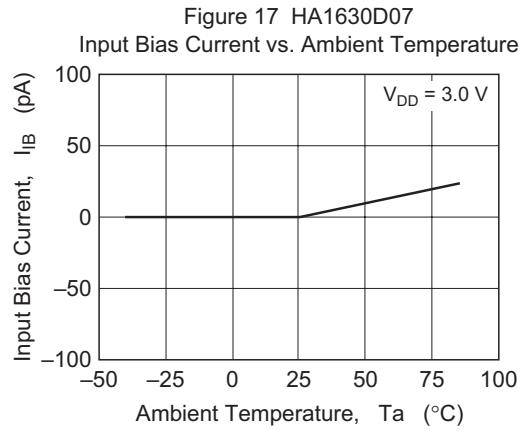
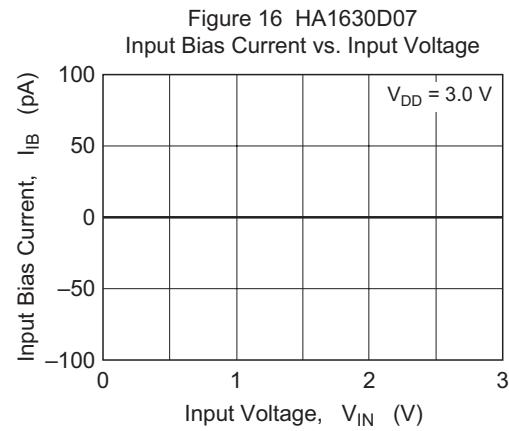
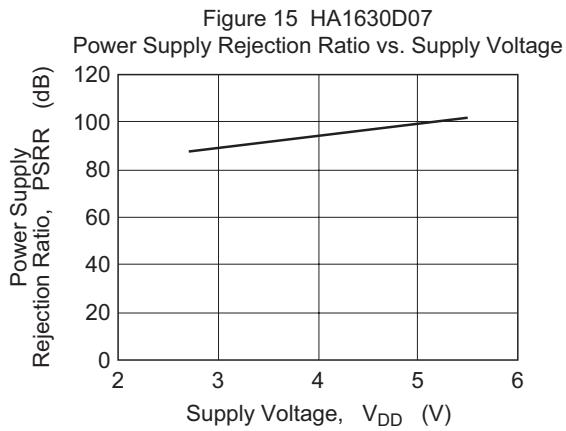
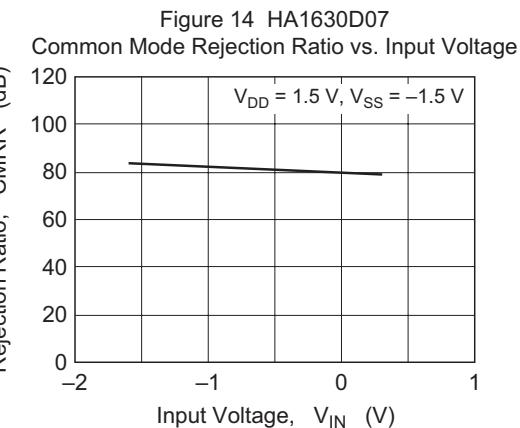
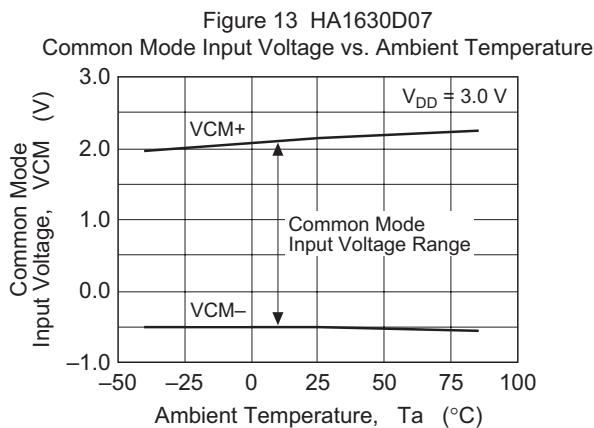
Figure 6 HA1630D07
Output Source Current vs. Ambient Temperature



Characteristic Curves (cont.)



Characteristic Curves (cont.)



Characteristic Curves (cont.)

Figure 19 HA1630D07
Slew Rate (rising) vs. Ambient Temperature

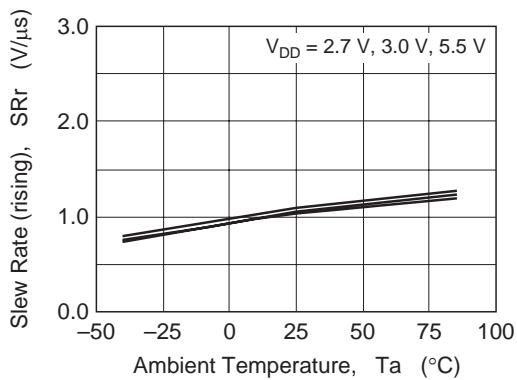


Figure 20 HA1630D07
Slew Rate (rising)

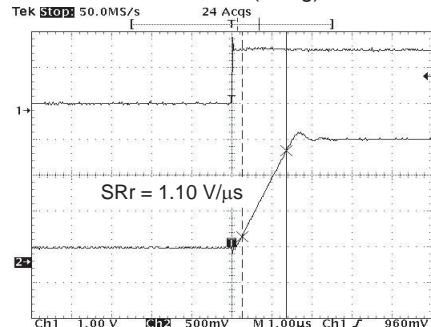


Figure 21 HA1630D07
Slew Rate (falling) vs. Capacitive Load

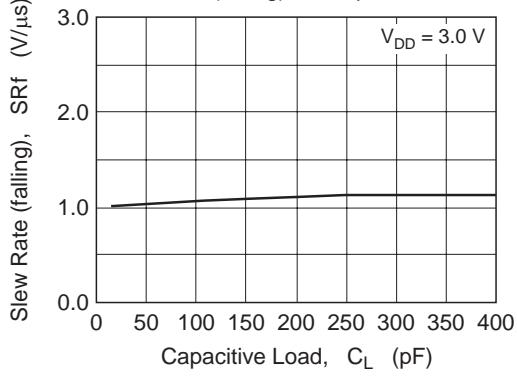


Figure 22 HA1630D07
Slew Rate (falling) vs. Ambient Temperature

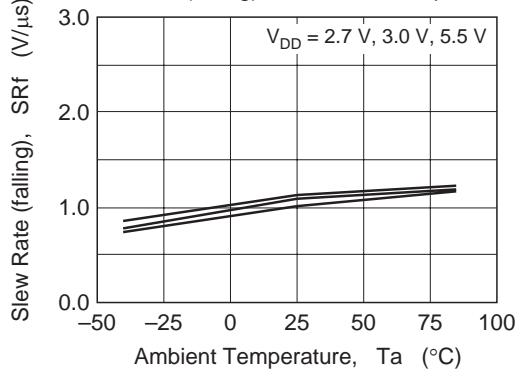


Figure 23 HA1630D07
Slew Rate (falling)

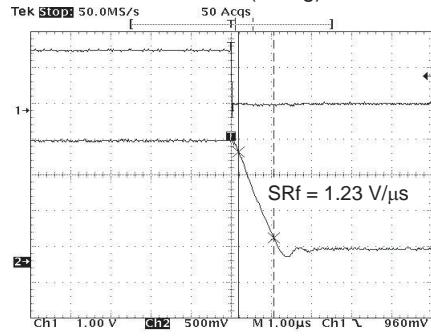
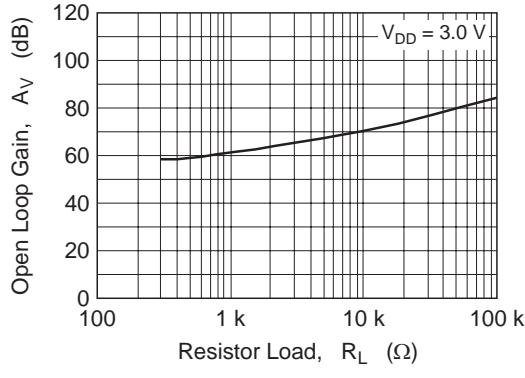
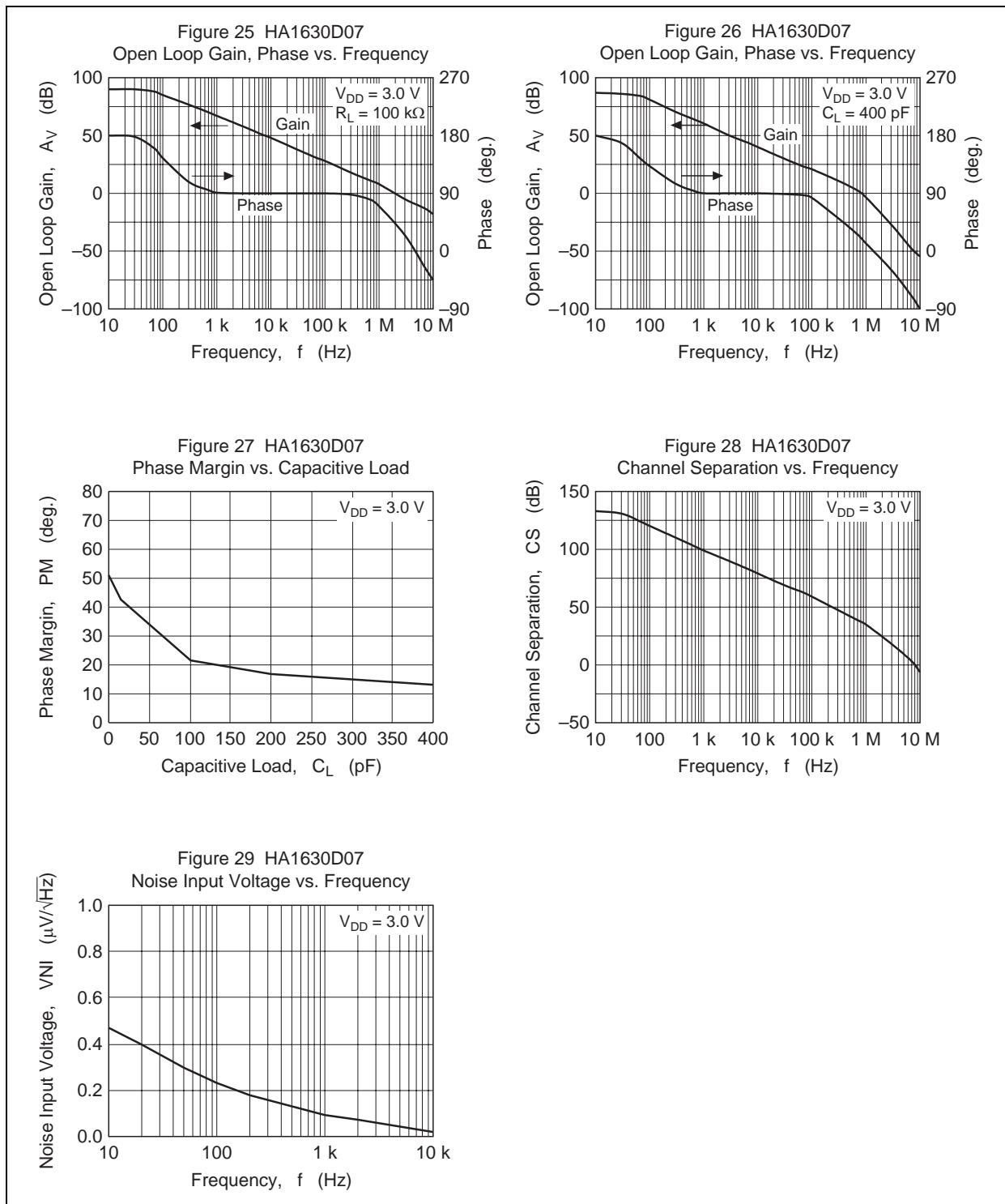


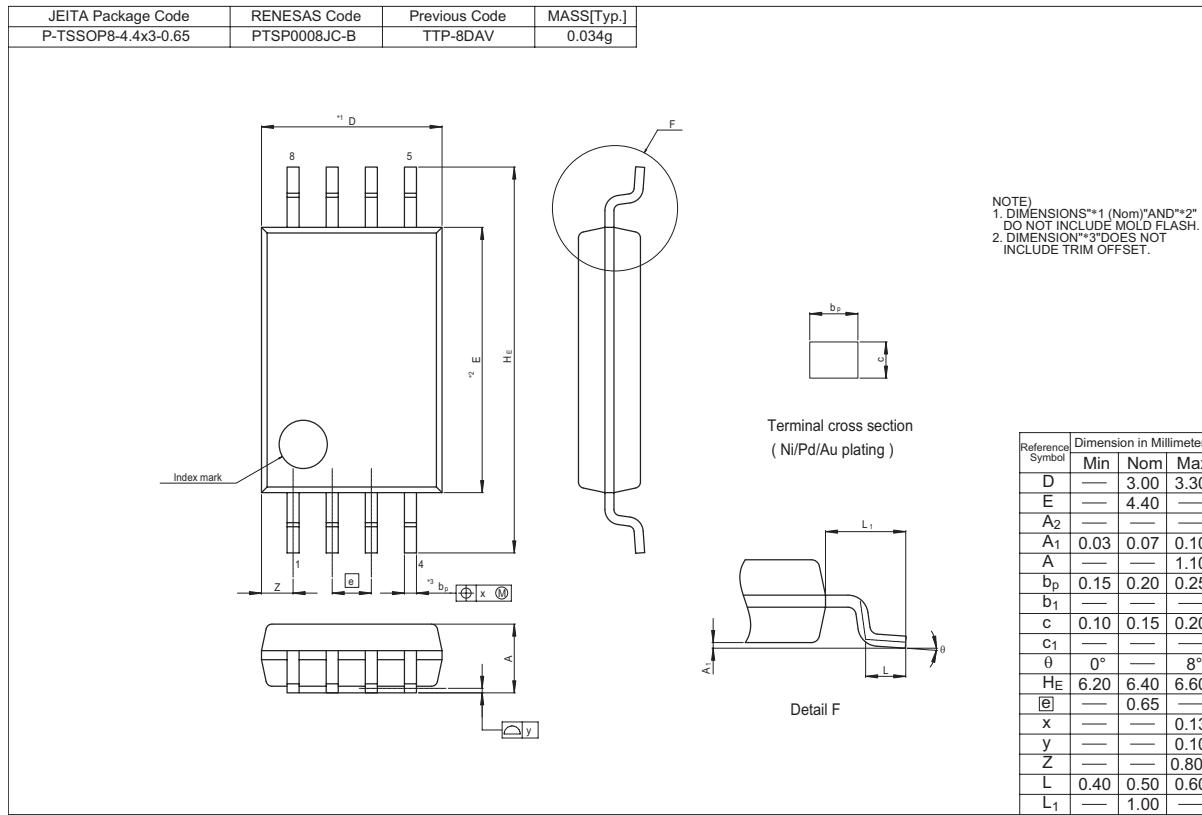
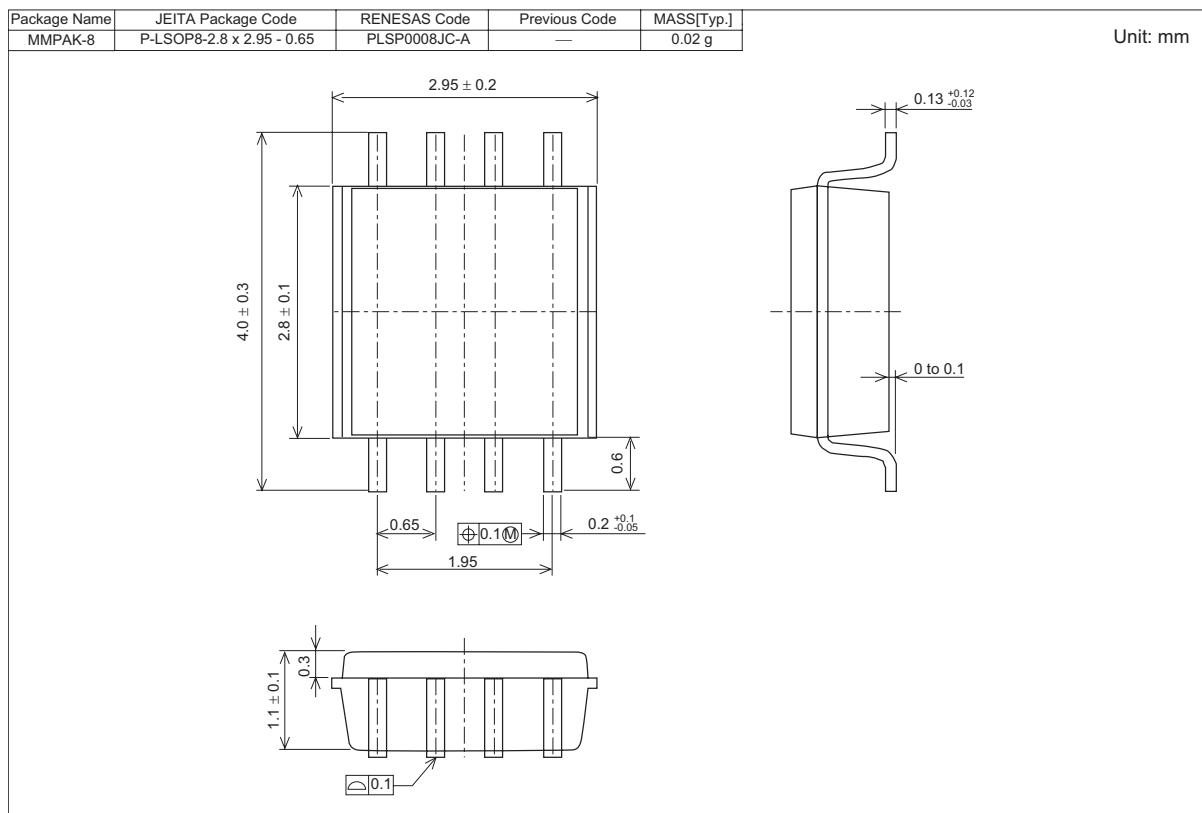
Figure 24 HA1630D07
Open Loop Gain vs. Resistor Load



Characteristic Curves (cont.)



Package Dimensions



Taping & Reel Specification

[Taping]

Package Code	W	P	A ₀	B ₀	K ₀	E	F	D ₁	Maximum Storage No.
TSSOP-8	12	8	6.9	3.6	1.7	1.75	5.5	1.5	3,000 pcs/reel
MMPAK-8	12	4.0	3.15	4.35	—	—	5.5	1.05	3,000 pcs/reel

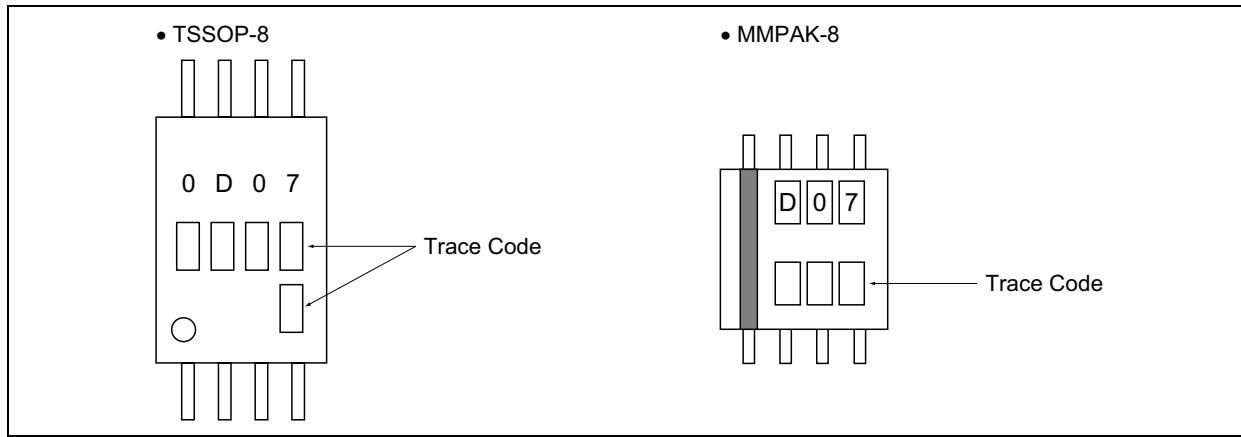
[Reel]

Package	Tape width	W1	W2	A
TSSOP-8	12	17.4	13.4	330
MMPAK-8	12	17.0	13.0	178

[Ordering Information]

Ordering Unit
3,000 pcs

Mark Indication



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